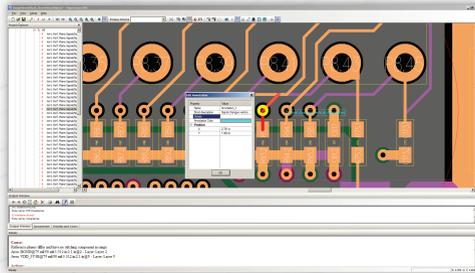
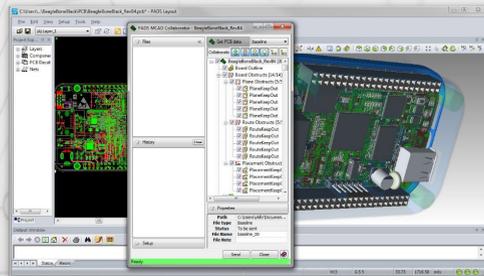


DESIGN RULE CHECKING (DRC)



Identify complex electrical rule violations that affect design integrity and performance. PADS HyperLynx DRC uses pre-defined SI/PI rules to find problems such as traces crossing splits and voids, and traces with reference plane changes.

ECAD <-> MCAD COLLABORATION



PTC®

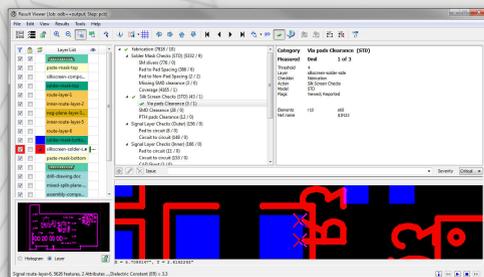
SOLIDWORKS

CATIA

PLM Software
SIEMENS
NX

Collaborate with MCAD designers directly from within PADS, regardless of which mechanical system is used. PADS is the only multi-MCAD integration platform that uses ProSTEP-approved data exchange methodologies.

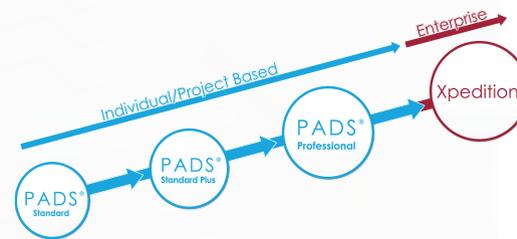
DESIGN FOR MANUFACTURING



Identify issues that cause production delays using 100+ of the most critical fabrication and assembly checks. Find and resolve problems such as resist slivers, unintended copper exposed by soldermasks, and improper testpoint-to-testpoint spacing.

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SCALABILITY



Products change and grow and so do companies. As such, it's important to consider scalability when choosing a design tool. PADS is with you every step of the way, providing the technology required as your needs grow.

Free evaluations and more information at pads.com

PADS®

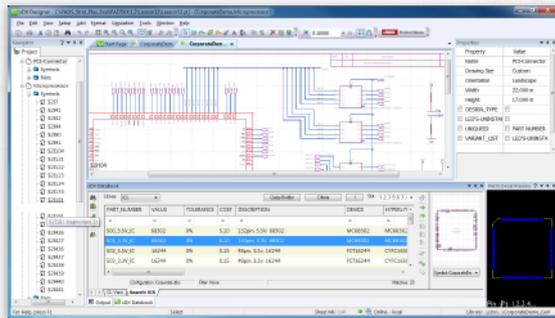
PRODUCT CREATION



Mentor®
A Siemens Business

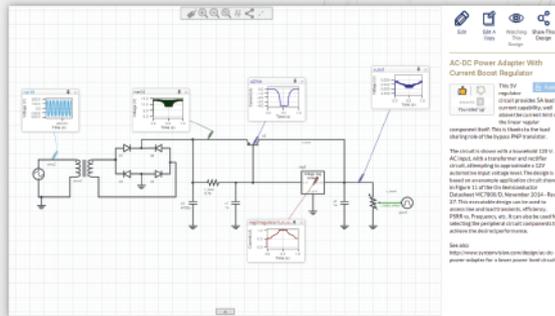
The platform for innovators and small teams designing high-quality electronic products from concept to reality.

SCHEMATIC DESIGN



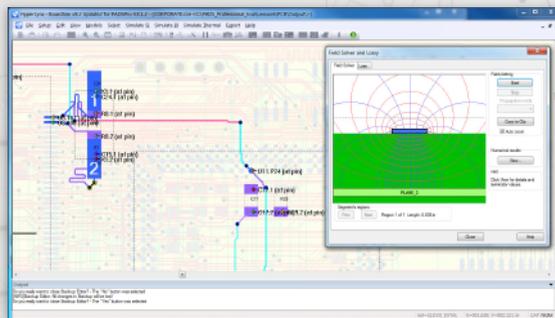
Capturing a design should be simple, easy to accomplish, and error-free. With PADS, you can consider cost and reliability from the beginning of the product-creation process to create a clean design that is easy to verify and manage.

ANALOG / MIXED-SIGNAL



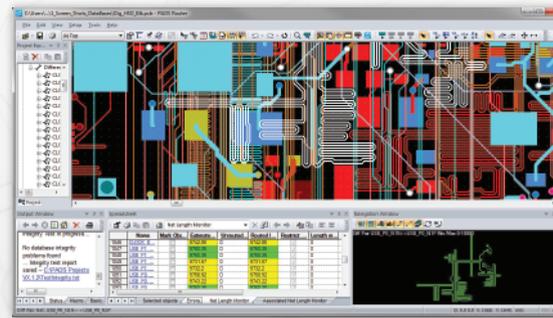
Cloud-based circuit exploration is included with every PADS suite. Need more? Use PADS AMS Design Suite to create, simulate, and validate analog, mixed-signal, and mixed-technology circuits.

SIGNAL INTEGRITY



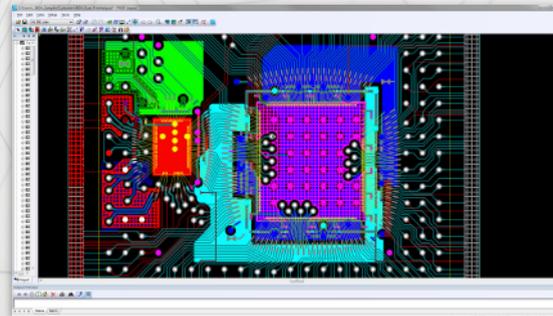
Analyze signal integrity before and after layout to identify potential issues that can affect electrical quality within the design and provide guidance on solution validation.

ADVANCED LAYOUT & ROUTING



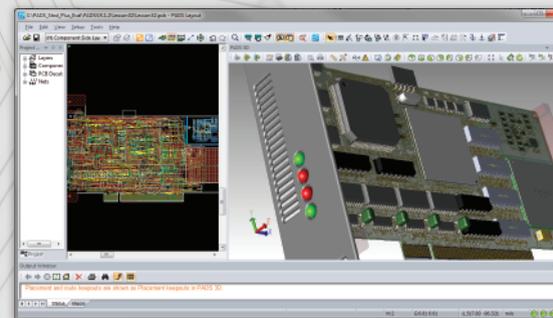
Complete designs quickly with powerful layout, interactive and automatic routing, and advanced design features for physical design reuse, RF, and high-speed routing. Create and verify design constraints at any point in the design process.

ADVANCED PACKAGING



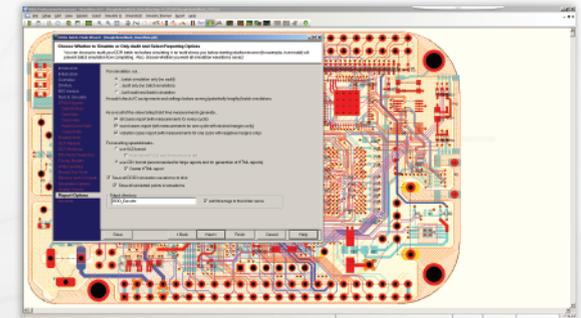
Easily design and place bare-die components on chip-on-board (COB) and multi-chip modules (MCM), and on single-chip and chip-scale packages (CSPs).

3D VISUALIZATION & HAZARD DETECTION



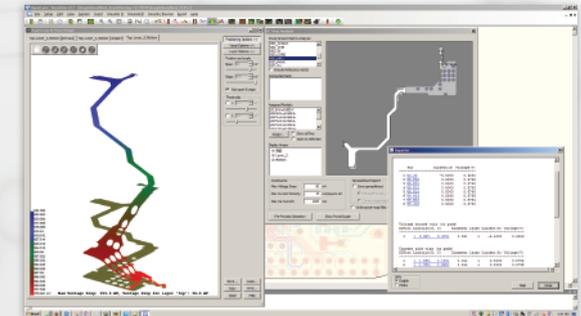
Use photorealistic 3D views to place components in 2D or 3D and to inspect your board prior to manufacturing. Support for STEP and other models enables placement and DRC hazard detection for full design validation.

DDR ANALYSIS



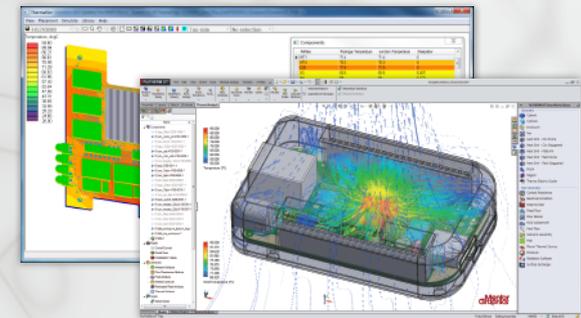
PADS HyperLynx® DDR reduces design and debug cycles by identifying weaknesses in DDR1/2/3 and LPDDR1/2/3 designs. Detailed simulations take board-level effects into account, providing a comprehensive view of your memory interface.

DC DROP



Quickly analyze voltage drop of power rails due to insufficient copper with PADS HyperLynx DC Drop. You'll detect and resolve issues early in the design, minimizing costs and design time.

THERMAL ANALYSIS



Conduct "what-if" analysis on component placement, stack-up design, and mechanical cooling techniques. Then use PADS FloTHERM® XT to explore the heating effects of package selection, PCB layout, and board structure within an enclosure.